Abstracts

Microwave Packaging of Optoelectronic Components

J. Schlafer and R.B. Lauer. "Microwave Packaging of Optoelectronic Components." 1990 Transactions on Microwave Theory and Techniques 38.5 (May 1990 [T-MTT] (Special Issue on Applications of Lightwave Technology to Microwave Devices, Circuits, and Systems)): 518-523.

The design and performance characteristics of single-mode fiber-coupled laser and photodiode packages suitable for use in microwave RF or broad-band transmission systems are discussed. The necessary packaging considerations to achieve laser and photodiode performance to 20 GHz are described. Mechanical, thermal, optical, and microwave details of two laser packages and one photodiode package are given and the optoelectronic characteristics of the packaged units are presented and discussed. It is seen that the intrinsic optoelectronic performance of the components is preserved to at least 20 GHz and that this performance is not affected by package design.

❑ Return to main document.